

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

Assignment ID: PATI924898

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the Assignee previously recorded on Reel 70418 Frame 916. Assignor(s) hereby confirms the Assignment.
CONVEYING PARTY DATA	
Name	Execution Date
PEP INNOVATION PTE LTD	12/30/2024
RECEIVING PARTY DATA	
Company Name:	CR Runan Technologies (Chongqing) Co. Ltd.
Street Address:	Room 216, Building D, Xiyong Avenue No. 25
Internal Address:	Shapingba District
City:	Chongqing
State/Country:	CHINA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Patent Number:	11881415
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2673932299
Email:	docketing@pacificpatentgroup.com
Correspondent Name:	Mr. Jun Ye
Address Line 1:	203 N LaSalle, Suite 2100
Address Line 4:	Chicago, ILLINOIS 60601
ATTORNEY DOCKET NUMBER:	81901-000006
NAME OF SUBMITTER:	Noemi Tovar
SIGNATURE:	/Noemi Tovar/
DATE SIGNED:	03/31/2025
Total Attachments: 25	
source=81901-000006-Corrective-Assignment for PEP-Innovation-Licensing Agreement to CR Runan Tech-as-filed-3-31-25#page1.tiff	
source=81901-000006-Corrective-Assignment for PEP-Innovation-Licensing Agreement to CR Runan Tech-as-filed-3-31-25#page2.tiff	
source=81901-000006-Corrective-Assignment for PEP-Innovation-Licensing Agreement to CR Runan Tech-as-filed-3-31-25#page3.tiff	

[illegible]

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

Assignment ID: PATI867432

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	LICENSE	
CONVEYING PARTY DATA		
	Name	Execution Date
	PEP INNOVATION PTE LTD	12/30/2024
RECEIVING PARTY DATA		
<u>CR Runan Technologies (Chongqing) Co. Ltd.</u>		
Company Name:	CR Runan Technologies (Chongqing) Co. Ltd.	
Street Address:	Room 216, Building D, Xiyong Avenue No. 25	
Internal Address:	Shapingba District	
City:	Chongqing	
State/Country:	CHINA	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Patent Number:	11881415
CORRESPONDENCE DATA		
Fax Number:		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	2673932299	
Email:	docketing@pacificpatentgroup.com	
Correspondent Name:	Mr. Jun Ye	
Address Line 1:	203 N LaSalle, Suite 2100	
Address Line 4:	Chicago, ILLINOIS 60601	
ATTORNEY DOCKET NUMBER:	81901-000006	
NAME OF SUBMITTER:	Noemi Tovar	
SIGNATURE:	/Noemi Tovar/	
DATE SIGNED:	03/05/2025	
Total Attachments: 23		
source=81901-000006-PEP-Innovation-Licensing Agreement to CR Runan Tech-as-filed-3-5-25#page1.tiff		
source=81901-000006-PEP-Innovation-Licensing Agreement to CR Runan Tech-as-filed-3-5-25#page2.tiff		
source=81901-000006-PEP-Innovation-Licensing Agreement to CR Runan Tech-as-filed-3-5-25#page3.tiff		
source=81901-000006-PEP-Innovation-Licensing Agreement to CR Runan Tech-as-filed-3-5-25#page4.tiff		
source=81901-000006-PEP-Innovation-Licensing Agreement to CR Runan Tech-as-filed-3-5-25#page5.tiff		
source=81901-000006-PEP-Innovation-Licensing Agreement to CR Runan Tech-as-filed-3-5-25#page6.tiff		

STATEMENT BY TRANSLATOR

I hereby confirm that the English translation enclosed herewith is an accurate translation of the Technology License Agreement originally in Chinese.

I declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Date 2025.02.24

By: LI Long
Name in Print: LI Long

TECHNOLOGY LICENSING AGREEMENT

THIS TECHNOLOGY LICENSE AGREEMENT (hereinafter referred to as "this Agreement") is made on [December] [30], 2024, at Shapingba District, Chongqing, People's Republic of China, by and between:

SiPLP Microelectronics (Chongqing) Limited (hereinafter referred to as "Party A"), a limited liability company established and existing under the laws of the PRC, with its registered address at Building C, No. 25, Xiyong Avenue, Shapingba District, Chongqing, China.

PEP INNOVATION PTE LTD (hereinafter referred to as "Party B"), a limited liability company established and existing under the laws of Singapore, with its registered address at 8, Admiralty Street, Admirax Building, #01-07/10, Singapore 757438.

(Party A and Party B are hereinafter referred to individually as a "Party" and collectively as the "Parties".)

1 GENERAL PROVISIONS

1.1 Definitions

Unless otherwise provided in the terms or context of this Agreement, the following terms shall have the meanings set forth below:

"Affiliate" means any company, enterprise, or other entity which, directly or indirectly controls a party, is under common control with a party, or is controlled by a party, through ownership of voting shares, registered capital, or otherwise; and the term "control" means owning fifty percent (50%) or more of the voting shares or registered capital of a company, enterprise, or other entity, or having the right to appoint a majority of the directors of an enterprise, company, or other entity, or having the right to direct the operating management of an enterprise, company, or other entity.

The **"patented technologies for panel-level packaging"** means the patented technologies for panel-level packaging owned by Party B as the patentee or patent applicant. A list of the patented technologies for panel-level packaging is set out in Annex 2 to this Agreement.

"China" means the mainland region of the People's Republic of China, and or the purposes of this Agreement only, excludes the Hong Kong Special Administrative Region, the Macau Special Administrative Region, and the Taiwan region.

"Global territory" means any country or region within or outside China on a global scale.

2

3 LICENSE OF THE PATENTED TECHNOLOGIES FOR PANEL-LEVEL PACKAGING

3.1 Party B grants to Party A and Party A's Affiliates, CR Runan Technologies (Chongqing) Co. Ltd. (hereinafter referred to as "CR Runan"), with respect to the patented technologies for panel-level packaging, on the following terms and conditions:

- (a) an exclusive, conditional sublicensable or transferable (subject to Article 3.2), irrevocable, and royalty-free license within the territory of China, with a term from June 1, 2018, to December 31, 2027 (hereinafter referred to as the "exclusive license period").
- (b) a non-exclusive, conditional sublicensable or transferable (subject to Article 3.2), irrevocable, and royalty-free license in countries and territories within the global territory other than China during the exclusive license period.
- (c) a non-exclusive, conditional sublicensable or transferable (subject to Article 3.2), irrevocable, and royalty-free license within the global territory after the expiration of the exclusive license period, and the period of the non-exclusive license is the duration of the existence of CR Runan.

3.2 During the license period set forth in Article 3.1, without Party B's written consent, Party A or CR Runan shall not grant any third party to use the patented technologies for panel-level packaging in any way, in any territory, and in the form of a transfer of license authorization or sublicense, unless such third party is an Affiliate of Party A or CR Runan.

3.3 Party B shall take all necessary actions as soon as possible after the signing of this Agreement to cooperate with Party A and CR Runan in the recordation of the patent license with respect to the patents in Annex 2 which have been granted. For other patents that have not been granted on the date of this Agreement, Party B shall take all necessary actions as soon as possible within one (1) month after a license is granted, with respect to the newly granted patents, to cooperate with Party A and CR Runan in the recordation of the granted patents.

4

5

6

7

8

9

10 RESOLUTION OF DISPUTES

Any dispute arising out of or in connection with this Agreement and the annexes hereunder, supplementary agreements, etc. (if any) shall be settled by the parties through negotiation and may also be mediated by the relevant authorities. If the negotiation or mediation fails, a lawsuit shall be brought to a people's court with jurisdiction as provided by law.

11 GOVERNING LAW

The formulation and interpretation of this Agreement and the settlement of disputes arising in the course of its execution or in connection with this Agreement shall be governed by the laws currently in force in China.

13 MISCELLANEOUS

13.1 Entry into force of the Agreement

This Agreement shall be effective from the date of signature and stamping by both Party A and Party B. This Agreement shall be valid for the legal successors of each party, and the legal successors shall be entitled to the rights under this Agreement and shall assume the obligations under this Agreement.

13.2 Number of copies

This Agreement is made in quadruplicate, with each party holding two copies.

(The following, without the text of the agreement, is the signature page of the technology license agreement between Party A, SIPLP MICROELECTRONICS (CHONGQING) LIMITED, and Party B, PEP INNOVATION PTE LTD)

IN WITNESS WHEREOF, the duly authorized representatives of the parties have entered into this Agreement on the date set forth on the first page hereof, at Shapingba District, Chongqing, China:

Party A: SiPLP Microelectronics (Chongqing) Limited (Official seal)

Signature: _____

Name:

Position:

PEP INNOVATION PTE LTD (Official seal)

Signature: _____

Name:

Position:

Annex 1

Annex 2: The list of the patented technologies for panel-level packaging

Annex 1

Annex 2: The list of the patented technologies for panel-level packaging

No.	Technology (Title)	Applicant	Publication Number	Publication date	Application number	Application date	type	type	Country	Notes
1										
2										
3										
4										
5										
6										
7	Semiconductor packaging method, semiconductor package and stacked semiconductor packages	Pep Innovation Pte Ltd	US10854531B2	2020-12-1	US15739939	2016-6-24	invention grant	invention grant	US	PCT/SG2016/050290 entry in US
8										
9										
10										
11										
12										
13										
14										
15	Semiconductor processing method	Pep Innovation Pte Ltd	US10504850B2	2019-12-10	US15752728	2016-8-12	invention grant	invention grant	US	PCT/SG2016/050385 entry in US
16	Method of packaging chip and chip package structure	Pep Innovation Pte Ltd	US11049734B2	2021-6-29	US15826268	2017-11-29	invention grant	invention grant	US	

17	Method of packaging chip and chip package structure	Pep Innovation Pte Ltd	US10615056B2	2020-4-7	US15826257	2017-11-29	invention grant	invention grant	US	
18										
19										
20										
21	Method of packaging chip and chip package structure	Pep Innovation Pte Ltd	US10431477B2	2019-10-1	US15826261	2017-11-29	invention grant	invention grant	US	
22										
23										
24										
25										
26										
27	Method of packaging chip and chip package structure	Pep Innovation Pte Ltd	US11881415B2	2024-1-23	US17346310	2021-6-14	invention grant	invention grant	US	Division of US15826268

技术许可协议

本技术许可协议(以下简称“本协议”)由以下双方于 2024 年【12】月【30】日在中华人民共和国重庆市沙坪坝区签订:

矽磐微电子(重庆)有限公司(以下简称“甲方”),一家根据中国法律成立和存续的有限责任公司,其注册地址为重庆市沙坪坝区西永大道 25 号 C 栋;和

PEP INNOVATION PTE LTD(以下简称“乙方”),一家根据新加坡法律成立并存续的有限责任公司,其法定地址为 8, Admiralty Street, Admirax Building, #01-07/10, Singapore 757438.

(甲方与乙方以下单独称为“一方”,合称为“双方”。)

1 总则

1.1 定义

除非本协议的条款或文义另有规定的,下列词语应具有以下规定的含义:

“关联方”指通过拥有具有投票权的股份、注册资本或其他方式直接或间接控制一方、与一方同受控制的或被一方控制的任何公司、企业或其他实体;“控制”一词的意思是拥有一家公司、企业或其他实体的具有投票权的股份或注册资本百分之五十(50%)或以上,或有权委任一家企业、公司或其他实体的多数董事,或有权领导一家企业、公司或其他实体的经营管理机构。

“面板级封装专利技术”是指乙方作为专利权人、专利申请人的面板级封装专利技术。面板级封装专利技术清单在本协议附件 2 中列明。

“中国”是指中华人民共和国大陆区域,仅为本协议之目的,不包括香港特别行政区、澳门特别行政区和台湾地区。

“全球区域”是指全球范围内,包括中国境内和境外任何国家和地区。

2

3 面板级封装专利技术许可

3.1 乙方按照如下条款与条件就面板级封装专利技术向甲方及甲方关联方:华润润安科技(重庆)有限公司(以下称“华润润安”):

- (a) 授予一项在中国境内的、独占的、在一定条件下可分许可或可转让许可的(见第3.2条)、不可撤销的且免许可费的许可,许可期限为2018年6月1日至2027年12月31日(以下称“独占许可期”);
- (b) 授予一项独占许可期内,在全球区域内除中国之外的国家和地区的非独占的、在一定条件下可分许可或可转让许可的(见第3.2条)、不可撤销的且免许可费的许可;
- (c) 授予一项在独占许可期届满后,在全球区域内的、非独占的、在一定条件下可分许可或可转让许可的(见第3.2条)、不可撤销的且免许可费的许可,该等非独占许可的期限为华润润安存续期间。

3.2 在第3.1条规定的许可期间内,未经乙方书面同意,甲方或华润润安不得将面板级封装专利技术以转让许可授权或分许可的形式授权任何第三方以任何方式、在任何区域使用,除非该第三方为甲方或华润润安的关联方。

3.3 乙方应在本协议签订后,尽快采取一切必需的行动,就已获得授权的附件2中的专利,配合甲方及华润润安进行专利许可备案。对于其他在本协议签订之日尚未获得



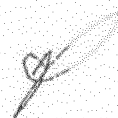
授权的专利，乙方应在获得授权后的一(1)个月内尽快采取一切必需的行动，就新
获得授权的专利，配合甲方及华润润安进行专利许可备案。

4

5

6

3 / 9



7

8

4 / 9

Handwritten signature or mark

9

10 争议的解决

因本协议以及本协议项下附件、补充协议等（如有）引起或有关的任何争议，由协议各方协商解决，也可由有关部门调解。协商或调解不成的，应向法律规定的有管辖权的人民法院起诉。

11 适用法律

本协议的制定、解释及其在执行过程中出现的或与本协议有关的纠纷之解决，受中国现行有效的法律的约束。

12

5 / 9



13 其他规定

13.1 协议的生效

本协议自甲乙双方签署盖章之日起生效。本协议对各方的法定承继方有效，上述法定承继方可享有本协议项下的权益并承担本协议项下的义务。

13.2 协议份数

本协议一式四份，协议各方各执两份。

2

(以下无正文, 为甲方矽磐微电子(重庆)有限公司与乙方 PEP INNOVATION PTE LTD 之间
技术许可协议的签字页)

本协议双方正式授权代表于本协议第一页所记载日期在中国重庆市沙坪坝区签订本协议,
特此为证:

甲方: 矽磐微电子(重庆)有限公司(公章)

签字: _____

姓名: _____

职务: _____



PEP INNOVATION PTE LTD(公章)

签字: _____

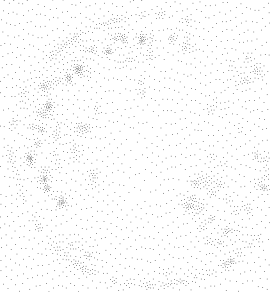
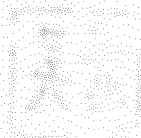
姓名: _____

职务: CEO

chew Hwee Seng



附件 1: 1



附件 2：面板级封装专利技术清单

附件 1

2

Column



